NSS1C201L, NSV1C201L

100 V, 3.0 A, Low $V_{CE(sat)}$ NPN Transistor

ON Semiconductor's e^{2}PowerEdge family of low $V_{CE(sat)}$ transistors are miniature surface mount devices featuring ultra low saturation voltage ($V_{CE(sat)}$) and high current gain capability. These are designed for use in low voltage, high speed switching applications where affordable efficient energy control is important.

Typical applications are DC−DC converters and power management in portable and battery powered products such as cellular and cordless phones, PDAs, computers, printers, digital cameras and MP3 players. Other applications are low voltage motor controls in mass storage products such as disc drives and tape drives. In the automotive industry they can be used in air bag deployment and in the instrument cluster. The high current gain allows e^{2}PowerEdge devices to be driven directly from PMU's control outputs, and the Linear Gain (Beta) makes them ideal components in analog amplifiers.

Features

- These Devices are Pb−Free, Halogen Free/BFR Free and are RoHS Compliant
- NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC−Q101 Qualified and PPAP Capable

MAXIMUM RATINGS (T_A = 25°C)

Rating	Symbol	Max	Unit
Collector-Emitter Voltage	V_{CEO}	100	Vdc
Collector-Base Voltage	V_{CBO}	140	Vdc
Emitter-Base Voltage	V_{EBO}	7.0	Vdc
Collector Current − Continuous	I_C	2.0	A
Collector Current − Peak	I_{CM}	3.0	A

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation T_A = 25°C Derate above 25°C	P_D (Note 1)	490 3.7	mW mW/°C
Thermal Resistance, Junction−to−Ambient	$R_{\theta JA}$ (Note 1)	255	°C/W
Total Device Dissipation T_A = 25°C Derate above 25°C	P_D (Note 2)	710 4.3	mW mW/°C
Thermal Resistance, Junction−to−Ambient	$R_{\theta JA}$ (Note 2)	176	°C/W
Junction and Storage Temperature Range	T_J, T_{stg}	−55 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. FR−4 @ 100 mm^2, 1 oz. copper traces.
2. FR−4 @ 500 mm^2, 1 oz. copper traces.

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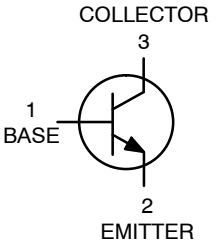
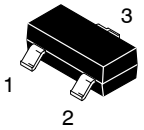
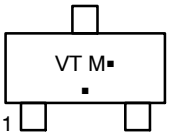
100 VOLTS, 3.0 AMPS NPN LOW $V_{CE(sat)}$ TRANSISTOR





SOT−23 (TO−236)
CASE 318
STYLE 6

MARKING DIAGRAM



VT = Specific Device Code
M = Date Code*
▪ = Pb−Free Package

(Note: Microdot may be in either location)

*Date Code orientation and/or overbar may vary depending upon manufacturing location.

ORDERING INFORMATION

Device	Package	Shipping†
NSS1C201LT1G, NSV1C201LT1G	SOT−23 (Pb−Free)	3000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
OFF CHARACTERISTICS					
Collector – Emitter Breakdown Voltage (I_C = 10 mAdc, I_B = 0)	$V_{(BR)CEO}$	100			Vdc
Collector – Base Breakdown Voltage (I_C = 0.1 mAdc, I_E = 0)	$V_{(BR)CBO}$	140			Vdc
Emitter – Base Breakdown Voltage (I_E = 0.1 mAdc, I_C = 0)	$V_{(BR)EBO}$	7.0			Vdc
Collector Cutoff Current (V_{CB} = 140 Vdc, I_E = 0)	I_{CBO}			100	nAdc
Emitter Cutoff Current (V_{EB} = 6.0 Vdc)	I_{EBO}			50	nAdc
ON CHARACTERISTICS					
DC Current Gain (Note 3) (I_C = 10 mA, V_{CE} = 2.0 V) (I_C = 500 mA, V_{CE} = 2.0 V) (I_C = 1.0 A, V_{CE} = 2.0 V) (I_C = 2.0 A, V_{CE} = 2.0 V)	h_{FE}	 150 120 80 40	 240	 360	
Collector – Emitter Saturation Voltage (Note 3) (I_C = 0.1 A, I_B = 0.01 A) (I_C = 0.5 A, I_B = 0.05 A) (I_C = 1.0 A, I_B = 0.100 A) (I_C = 2.0 A, I_B = 0.200 A)	$V_{CE(sat)}$			 0.030 0.060 0.090 0.150	V
Base – Emitter Saturation Voltage (Note 3) (I_C = 1.0 A, I_B = 0.100 A)	$V_{BE(sat)}$			 0.950	V
Base – Emitter Turn–on Voltage (Note 3) (I_C = 1.0 A, V_{CE} = 2.0 V)	$V_{BE(on)}$			 0.850	V
Cutoff Frequency (I_C = 100 mA, V_{CE} = 5.0 V, f = 100 MHz)	f_T		 110		MHz
Input Capacitance (V_{EB} = 2.0 V, f = 1.0 MHz)	Cibo		230		pF
Output Capacitance (V_{CB} = 10 V, f = 1.0 MHz)	Cobo		14		pF

3. Pulsed Condition: Pulse Width = 300 msec, Duty Cycle ≤ 2%.

TYPICAL CHARACTERISTICS

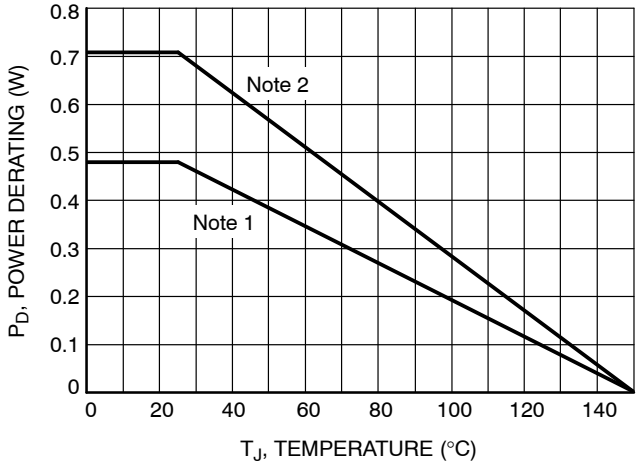


Figure 1. Power Derating

TYPICAL CHARACTERISTICS

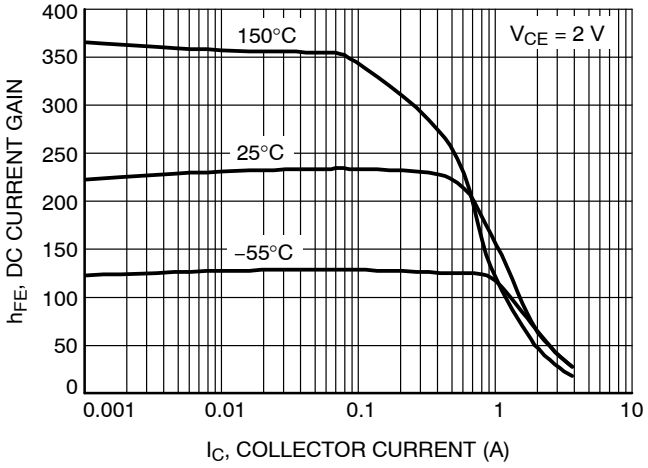


Figure 2. DC Current Gain

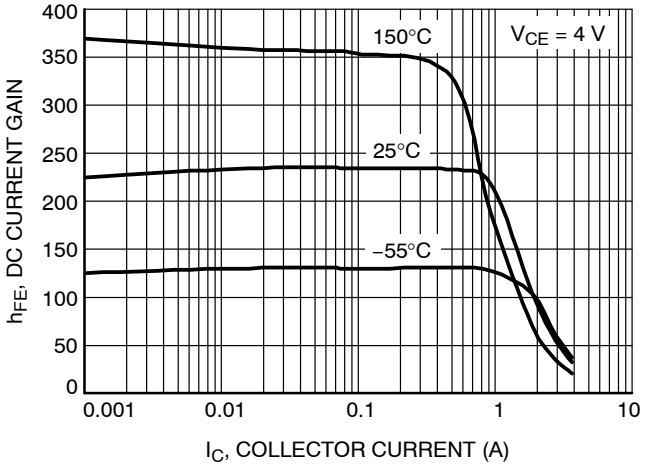


Figure 3. DC Current Gain

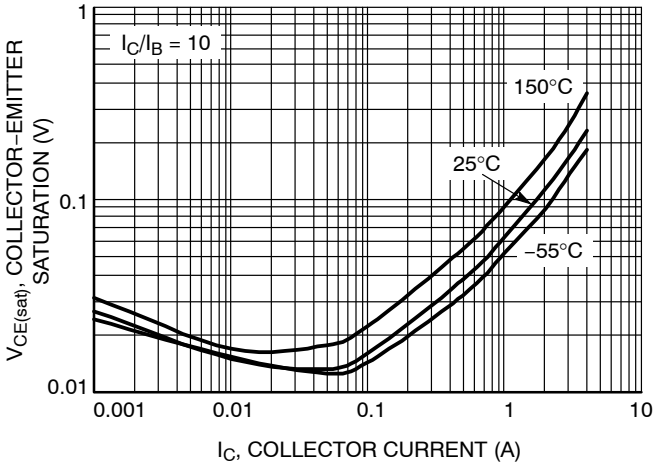


Figure 4. Collector−Emitter Saturation Voltage

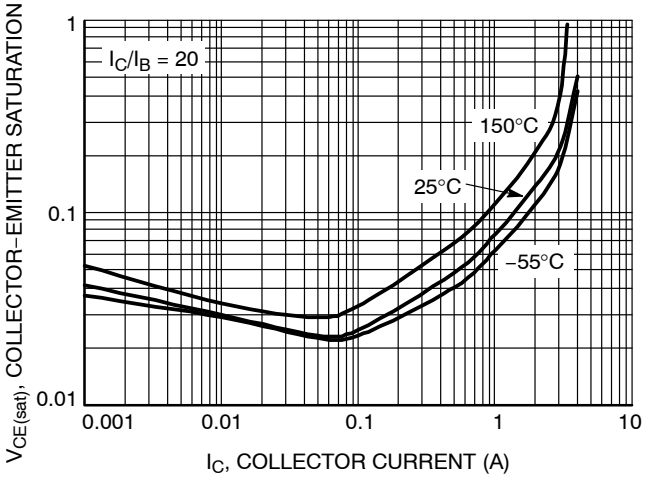


Figure 5. Collector−Emitter Saturation Voltage

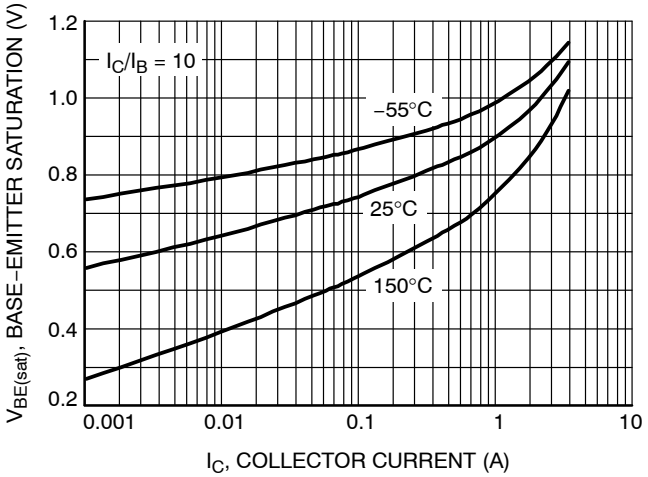


Figure 6. Base−Emitter Saturation Voltage

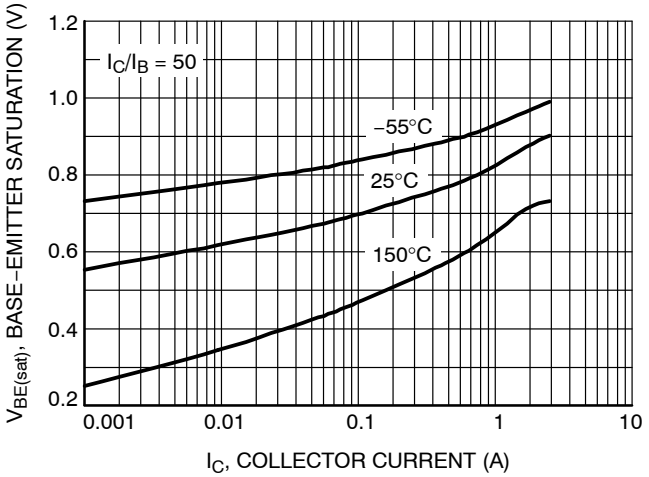


Figure 7. Base−Emitter Saturation Voltage

TYPICAL CHARACTERISTICS

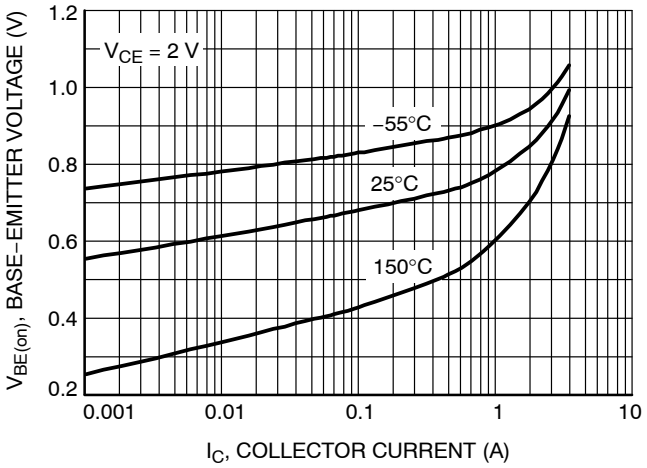


Figure 8. Base Emitter Voltage

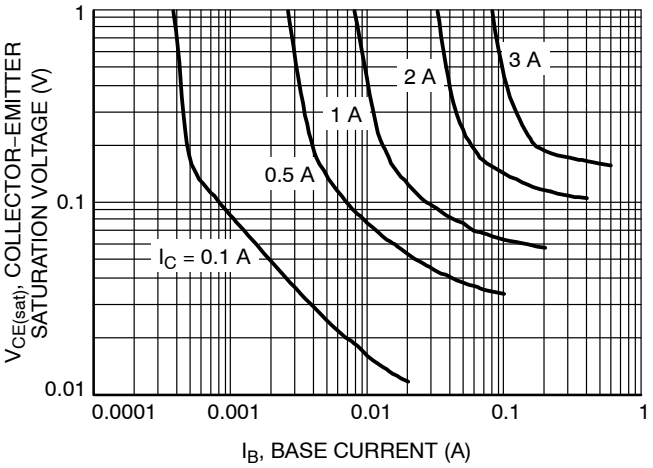


Figure 9. Collector Saturation Region

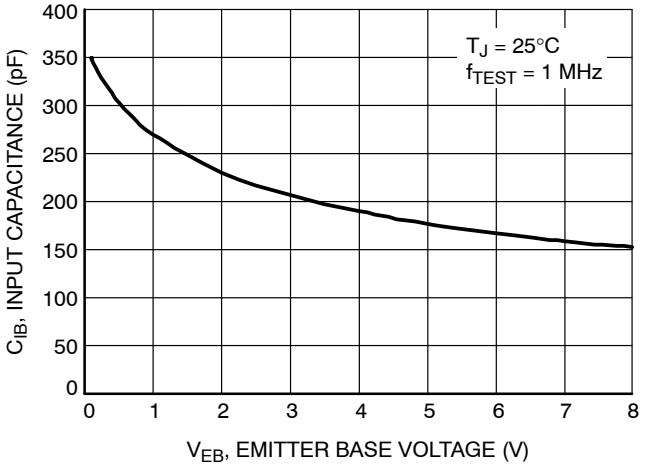


Figure 10. Input Capacitance

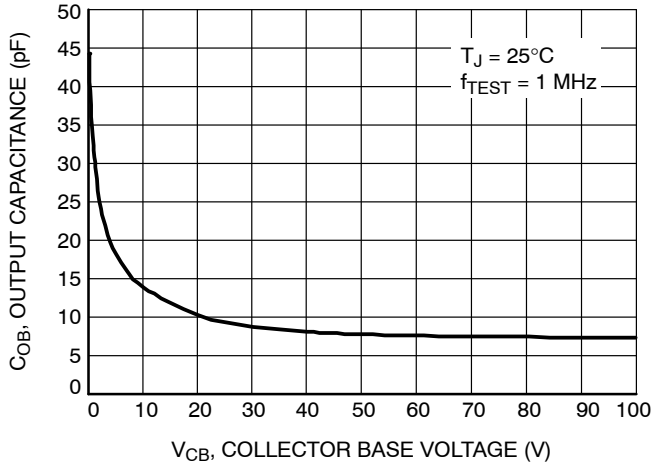


Figure 11. Output Capacitance

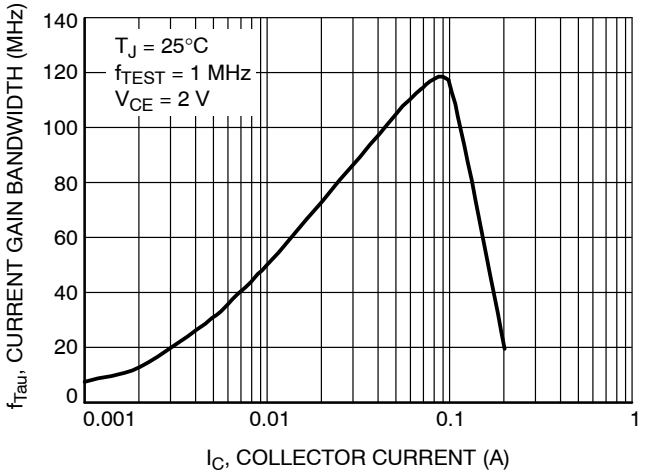


Figure 12. Current−Gain Bandwidth Product

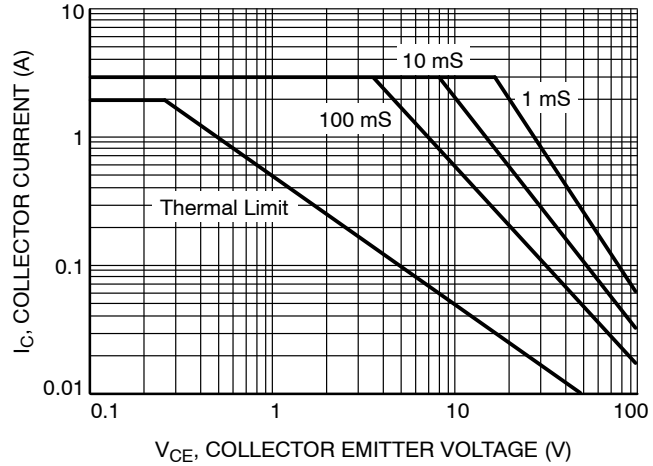
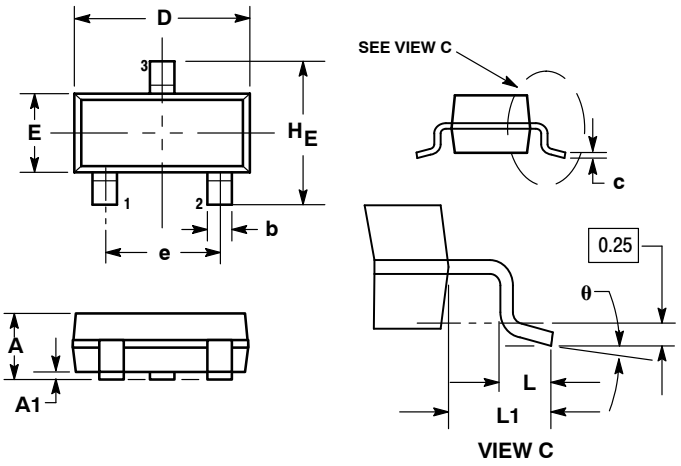


Figure 13. Safe Operating Area

PACKAGE DIMENSIONS

SOT−23 (TO−236)
CASE 318−08
ISSUE AN

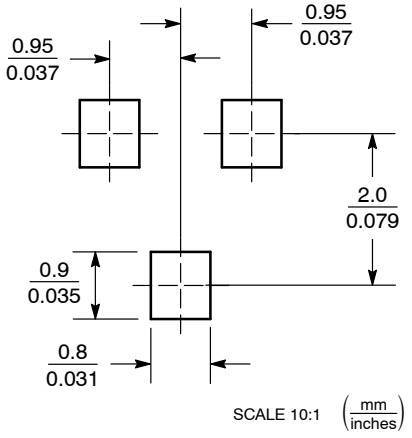


NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. 318−01 THRU −07 AND −09 OBSOLETE, NEW STANDARD 318−08.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
A	0.89	1.00	1.11	0.035	0.040	0.044
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.37	0.44	0.50	0.015	0.018	0.020
c	0.09	0.13	0.18	0.003	0.005	0.007
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
e	1.78	1.90	2.04	0.070	0.075	0.081
L	0.10	0.20	0.30	0.004	0.008	0.012
L1	0.35	0.54	0.69	0.014	0.021	0.029
H_E	2.10	2.40	2.64	0.083	0.094	0.104

STYLE 6:
PIN 1. BASE
2. EMITTER
3. COLLECTOR

SOLDERING FOOTPRINT*



*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:
Literature Distribution Center for ON Semiconductor
P.O. Box 5163, Denver, Colorado 80217 USA
Phone: 303−675−2175 or 800−344−3860 Toll Free USA/Canada
Fax: 303−675−2176 or 800−344−3867 Toll Free USA/Canada
Email: orderlit@onsemi.com

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